



X-832-054 A/B

Shin-Etsu Silicones of America, Inc.
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Product Description

Shin-Etsu's X-832-054 A/B is a dual component, room-temperature cure, phenyl-based polysiloxane potting gel that will cure to form a soft, pliable elastomer to protect sensitive electronic components. X-832-054 A/B provides superior vibration resistance and exhibits excellent, unprimed adhesion to metals, plastics, glass, and ceramics.

Product Features

- Superior vibration resistance
- Dual component
- 1:1 mix ratio
- Room-temperature cure

Typical Applications

- Protecting sensitive electronic components

Typical Properties

Type	Potting Gel
Cure Type	Addition
One/Two Component	Two
Color	Translucent
Density @ 23C (g/cm ³)	1.00
Viscosity A (cps)	700.00
Mix Ratio by weight	100:100
Cure Conditions	24hr @ 23C
Snap Time (min)	5
Penetration (1/10mm)	90
Usable Temperature Range (C)	-50 to +200

Note: Values are not for specification purposes.

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